Transistors

MSG430D4

SiGe HBT type

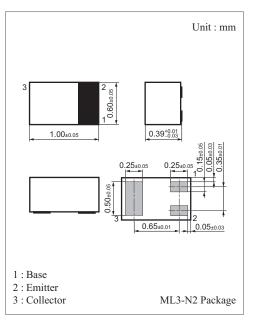
For low-noise RF amplifier

Features

- Compatible between high breakdown voltage and high cutoff frequency
- Low-noise, high-gain amplification
- Optimum for high-density mounting and downsizing of the equipment for Ultraminiature leadless package $0.6 \text{ mm} \times 1.0 \text{ mm}$ (height 0.39 mm)

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	9	V	
Collector-emitter voltage (Base open)	open) V _{CEO}		V	
Emitter-base voltage (Collector open)	V _{EBO}	1	V	
Collector current	I _C	100	mA	
Collector power dissipation *	P _C	100	mW	
Junction temperature	Tj	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Marking Symbol: 5Z

Note) Copper plate at the collector is 5.0 mm² on substrate at 10 mm \times 12 mm \times 0.8 mm.

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 9 V, I_E = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 6 V, I_B = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 1 \text{ V}, I_{C} = 0$			1	μΑ
Forward current transfer ratio	\mathbf{h}_{FE}	$V_{CE} = 3 \text{ V}, I_{C} = 15 \text{ mA}$	100		220	
Transition frequency *	f _T	V_{CE} = 3 V, I_{CI} = 30 mA, f = 2 GHz		14		GHz
Forward transfer gain *	$ S_{21e} ^2$	V_{CE} = 3 V, I_{CI} = 30 mA, f = 2 GHz	3.0	6.0		dB
Noise figure *	NF	V_{CE} = 3 V, I_{CI} = 15 mA, f = 2 GHz		1.6	2.2	dB
Collector output capacitance (Common base, input open circuited) *	C _{ob}	$V_{CB} = 3 V, I_{E} = 0, f = 1 MHz$		1.1	1.4	pF

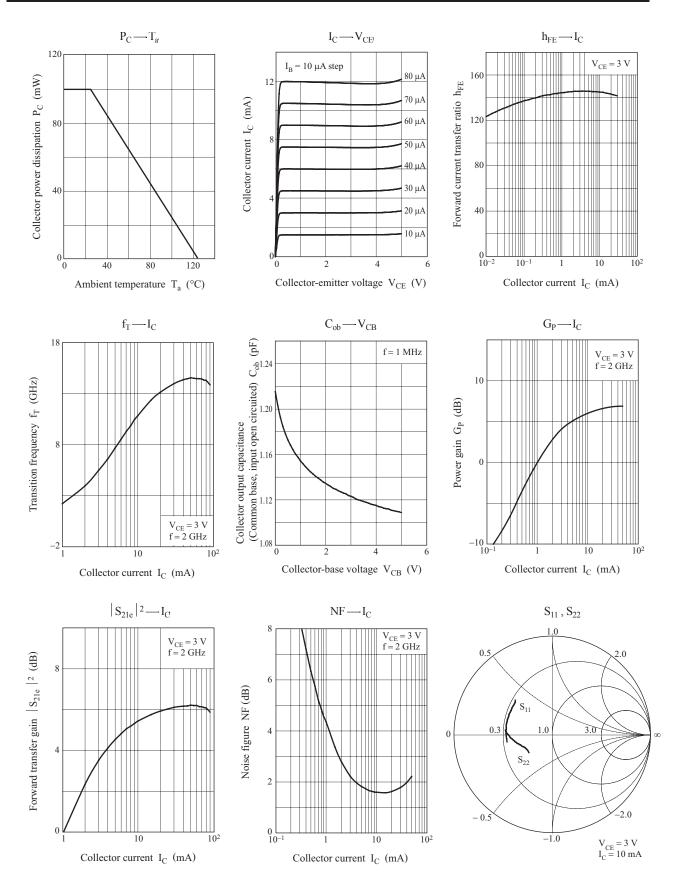
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Observe precautions for handling. Electrostatic sensitive devices.

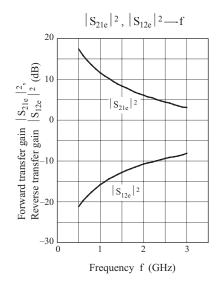
3. *: Verified by random sampling

MSG430D4

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